

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <u>www.onsemi.com</u>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor dates sheds, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor dates sheds and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights of others. ON Semiconductor products are not designed, intended, or authorized for use on similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor and its officers, employees, subsidiaries, affliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out or i, directly or indirectly, any lange of the applicatio customer's to unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the



N-Channel PowerTrench[®] MOSFET 100 V, 45 A, 6 m Ω

Features

- Max $r_{DS(on)} = 6 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 14 \text{ A}$
- Max $r_{DS(on)}$ = 11 m Ω at V_{GS} = 6 V, I_D = 11.5 A
- Advanced Package and Silicon combination for low r_{DS(on)} and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant



General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench[®] process thant has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Applications

- Primary DC-DC MOSFET
- Secondary Synchronous Rectifier
- Load Switch



Power 56

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter Drain to Source Voltage			Ratings	Units V	
V _{DS}				100		
V _{GS}	Gate to Source Voltage			±20	V	
I _D	Drain Current -Continuous	T _C = 25 °C		45		
	-Continuous	T _A = 25 °C	(Note 1a)	14	Α	
	-Pulsed			260		
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	541	mJ	
P _D	Power Dissipation	T _C = 25 °C		125		
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.7		
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C	

Thermal Characteristics

$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case	1.0	0 0 000
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note	la) 45	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86152	FDMS86152	Power 56	13 "	12 mm	3000 units

March 2015

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Chara	octeristics						
BV _{DSS}	Drain to Source Breakdown Voltage	$I_{D} = 250 \ \mu A, \ V_{GS} = 0 \ V$	100			V	
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu\text{A}$, referenced to 25 °C		90		mV/°C	
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μA	
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA	
On Chara	cteristics						
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$	2	3	4	V	
$\frac{\Delta V_{GS(th)}}{\Delta T_{J}}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \ \mu$ A, referenced to 25 °	C	-10		mV/°C	
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 14 A		5.2	6		
		V _{GS} = 6 V, I _D = 11.5 A	7.3 11		11	mΩ	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 14 \text{ A}, \text{ T}_{J} = 125 \text{ M}$	°C	8.7	10		
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 14 \text{ A}$		42		S	
Dynamic	Characteristics						
C _{iss}	Input Capacitance			2530	3370	pF	
C _{oss}	Output Capacitance	— V _{DS} = 50 V, V _{GS} = 0 V, — f = 1 MHz		595	795	pF	
C _{rss}	Reverse Transfer Capacitance			22	35	pF	
R _g	Gate Resistance			0.9		Ω	
Switching	Characteristics						
t _{d(on)}	Turn-On Delay Time			17	30	ns	
t _r	Rise Time	V _{DD} = 50 V, I _D = 14 A,		6	12	ns	
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$		25	39	ns	
t _f	Fall Time			5	10	ns	
Q _g	Total Gate Charge	$V_{GS} = 0 V$ to 10 V		36	50	nC	
Q _q	Total Gate Charge	$V_{GS} = 0 V \text{ to } 6 V$ $V_{DD} = 50 V$		23	33	nC	
Q _{gs}	Gate to Source Charge	I _D = 14 A		10.7		nC	
Q _{gd}	Gate to Drain "Miller" Charge			7.2		nC	
-	urce Diode Characteristics		1				
	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_S = 2.1 A$ (Note	e 2)	2) 0.70			
V _{SD}		$V_{GS} = 0 V, I_S = 14 A$ (Note	e 2)	0.78	1.3	- V	
t _{rr}	Reverse Recovery Time		,	59	94	ns	
	-	— I _F = 14 A, di/dt = 100 A/μs		-		+	

Notes:

1. R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 45 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 115 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.

3. Starting T_J = 25 °C, L = 3 mH, I_{AS} = 19 A, V_{DD} = 100 V, V_{GS} = 10 V. 100% test at L = 0.3 mH, I_{AS} = 42 A.



©2013 Fairchild Semiconductor Corporation FDMS86152 Rev.1.2





©2013 Fairchild Semiconductor Corporation FDMS86152 Rev.1.2

www.fairchildsemi.com



FDMS86152 N-Channel PowerTrench[®] MOSFET



ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor has against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death ass

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

© Semiconductor Components Industries, LLC